

VRW0656 ММ Ё QSQ Æ M ç s ll 1 Silicon NPN transistor in a SOT-323 Plastic Package.

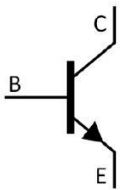
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High current, low voltage complementary pair with BC856W.

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General purpose switching and amplification.

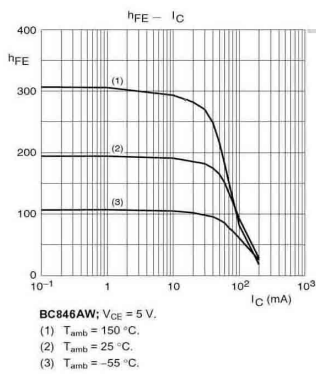
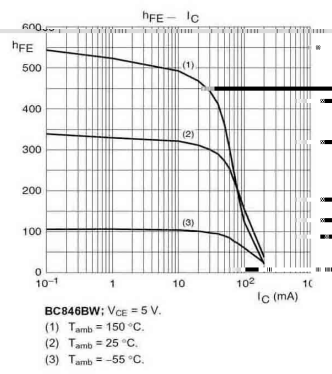
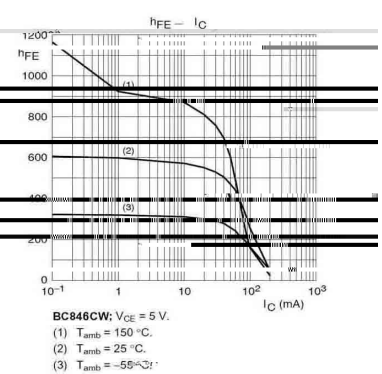
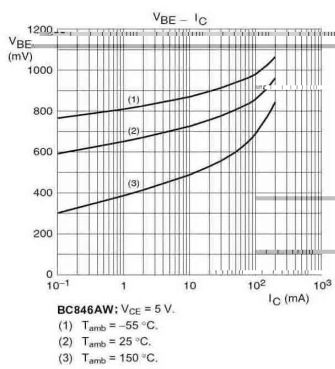
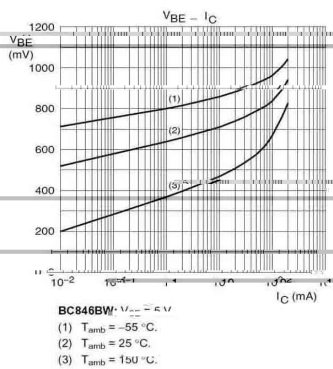
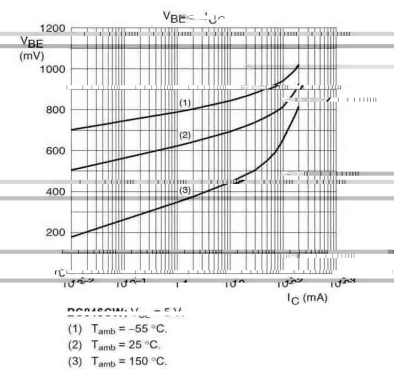
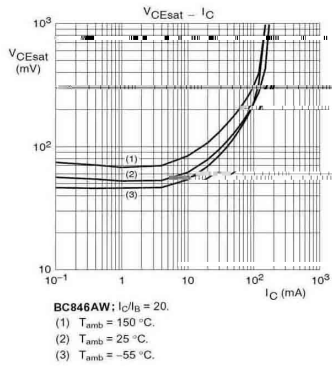
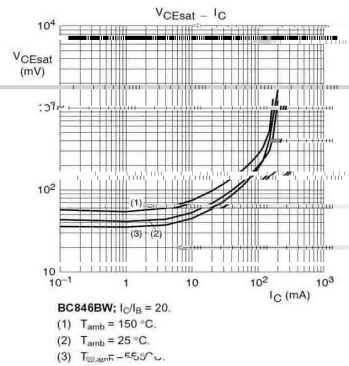
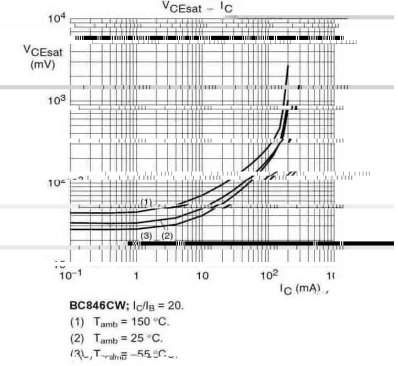
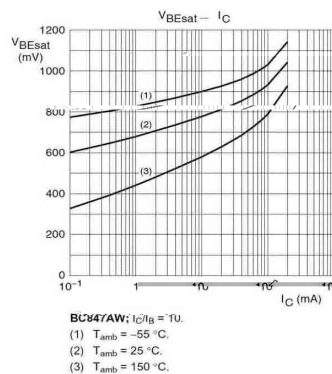
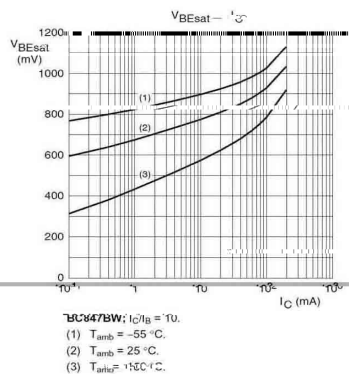
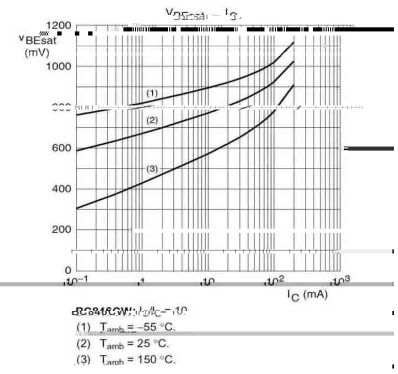
Ї ã ã ¨ ã ¨ з з Æ Н д ч / Equivalent Circuit



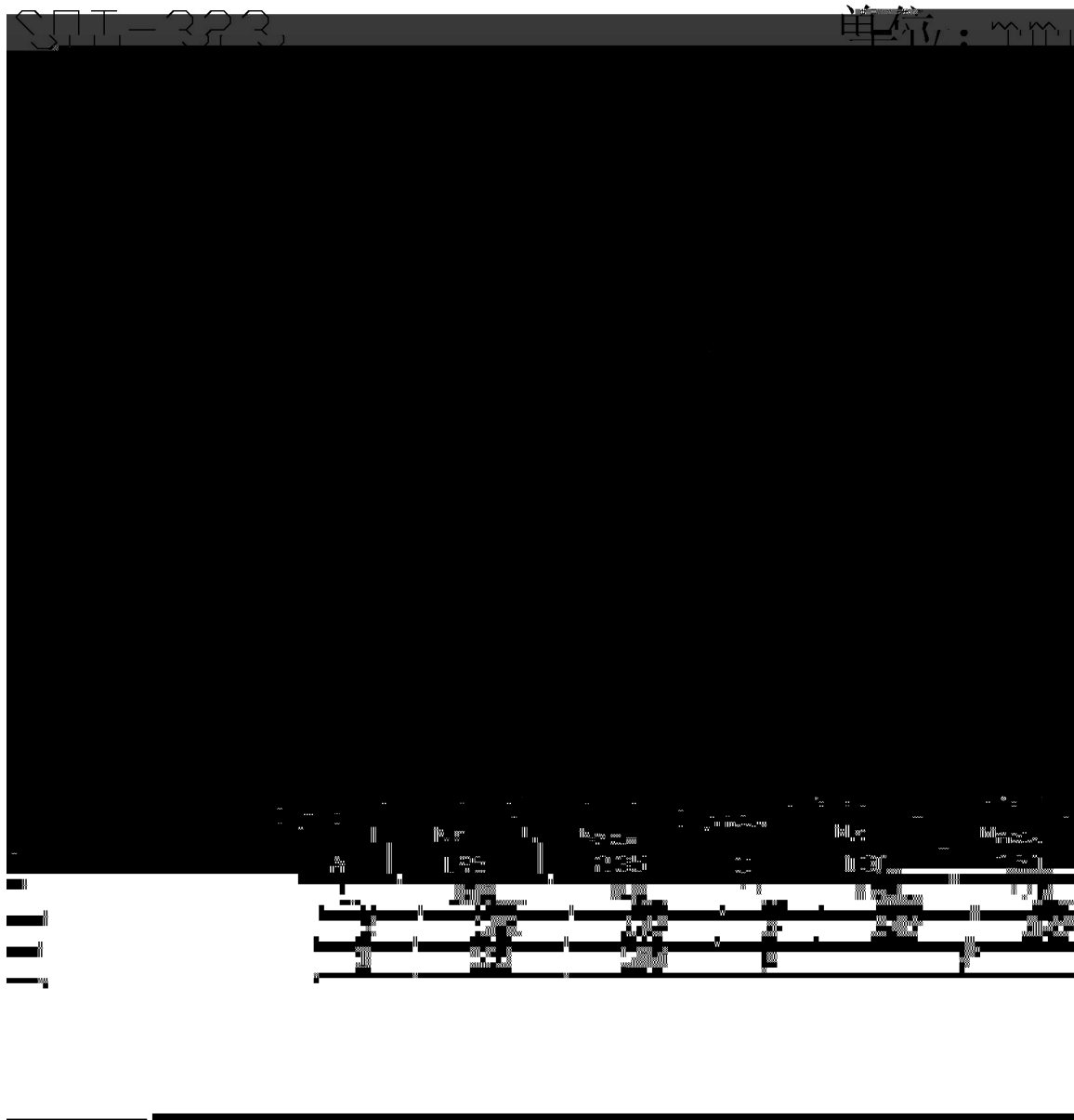
PIN1 χ

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	80	V
Collector to Emitter Voltage	V_{CEO}	65	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current - Continuous	I_C	100	mA

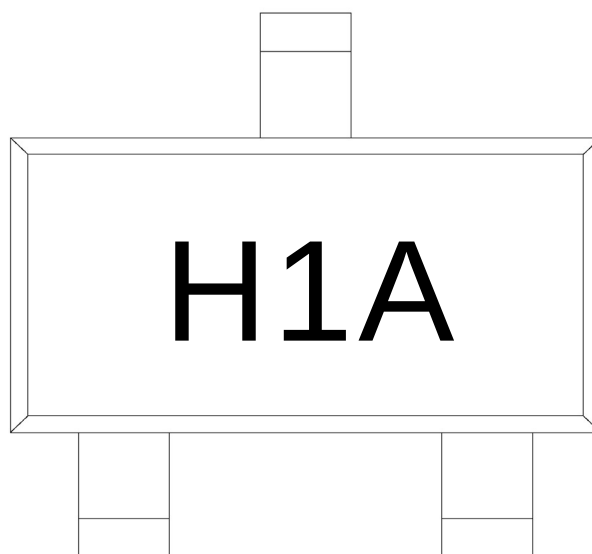
Electrical Characteristic Curve



⌘ É Ò Ì ð / Package Dimensions



1. 标记 / Marking Instructions



标记

H 公司代码

1 产品类型

A h_{FE} 分类符号

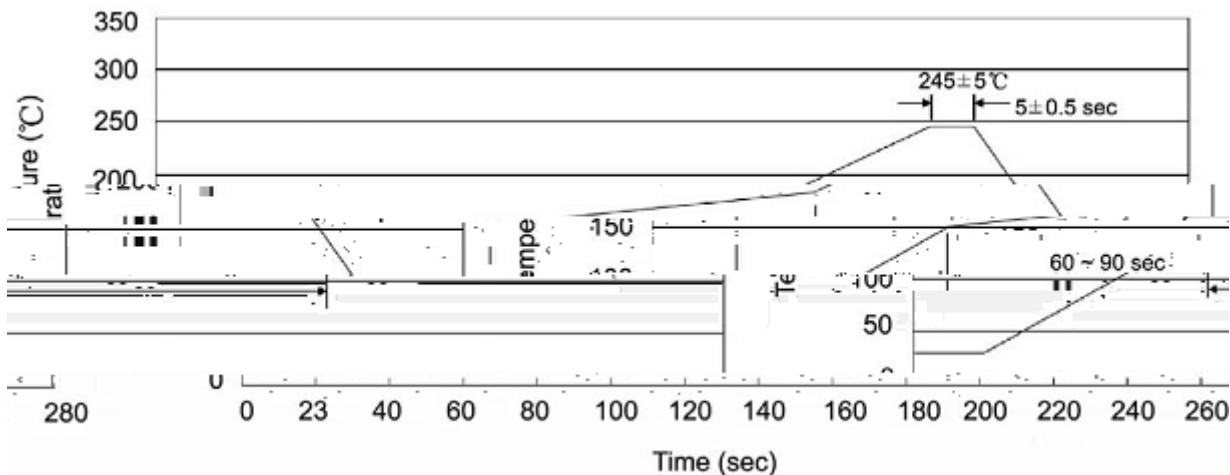
Note:

H: Company Code.

1: Product Type.

A: h_{FE} Classifications Symbol

Thermal Characteristics / Whp shudwxuh Suriloh i ru LU Uhior z Vroghulqj+Se0l uhh,



Characteristics

1. Preheating: 25~150 °C, Time: 60~90sec;
2. Peak Temp.: 245±5 °C, Duration: 5±0.5sec;
3. Cooling Speed: 2~10 °C/sec.

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Resistance to Soldering Heat Test Conditions

□ °C 260±5 Time: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

Packaging SPEC.

□ °C 260±5 Time: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

Package Type	Units					Dimension (unit mm ³)		

Notices